



Material Content Data Sheet



Sales Product Name		IPD60R385CP		Issued		19. July 2018		
MA#		MA001164292						
Package		PG-TO252-3-313		Weight*		320.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.064	1.58	1.58	15824	15824
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		460	
	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	copper	7440-50-8	147.096	45.96	46.02	459605	460203
wire	non noble metal	aluminium	7429-90-5	0.545	0.17	0.17	1704	1704
encapsulation	organic material	carbon black	1333-86-4	1.388	0.43		4336	
	plastics	epoxy resin	-	24.284	7.59		75877	
	inorganic material	silicondioxide	60676-86-0	113.096	35.34	43.36	353371	433584
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11686	11686
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4438	4449
solder	noble metal	silver	7440-22-4	0.100	0.03		314	
	non noble metal	tin	7440-31-5	0.080	0.03		251	
	non noble metal	lead	7439-92-1	3.836	1.20	1.26	11987	12552
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	5.99	6.00	59920	59998
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com